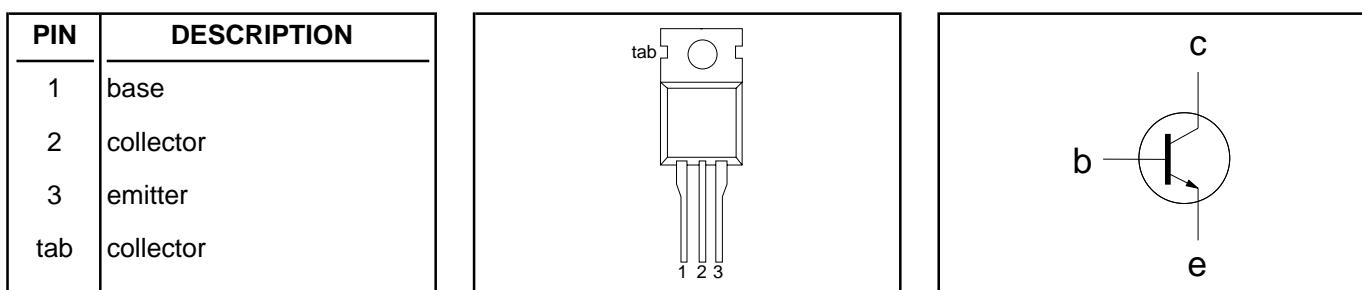


**Silicon Diffused Power Transistor****BUT211****GENERAL DESCRIPTION**

Enhanced performance, new generation, high speed switching npn transistor in TO220AB envelope specially suited for high frequency electronic lighting ballast applications.

**QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$V_{CESM}$	Collector-emitter voltage peak value	$V_{BE} = 0 \text{ V}$	-	850	V
$V_{CEO}$	Collector-emitter voltage (open base)		-	400	V
$I_C$	Collector current (DC)		-	5	A
$I_{CM}$	Collector current peak value		-	10	A
$P_{tot}$	Total power dissipation		-	100	W
$V_{CEsat}$	Collector-emitter saturation voltage		-	2.0	V
$t_f$	Inductive fall time	$T_{mb} \leq 25 \text{ }^\circ\text{C}$ $I_C = 3.0 \text{ A}; I_B = 0.4 \text{ A}$ $I_{Con} = 3.0 \text{ A}; I_{Bon} = 0.3 \text{ A}$	-	0.1	$\mu\text{s}$

**PINNING - TO220AB****PIN CONFIGURATION****SYMBOL****LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CESM}$	Collector-emitter voltage peak value	$V_{BE} = 0 \text{ V}$	-	850	V
$V_{CEO}$	Collector-emitter voltage (open base)		-	400	V
$I_C$	Collector current (DC)		-	5	A
$I_{CM}$	Collector current peak value		-	10	A
$I_B$	Base current (DC)		-	2	A
$I_{BM}$	Base current peak value		-	4	A
$P_{tot}$	Total power dissipation	$T_{mb} \leq 25 \text{ }^\circ\text{C}$	-	100	W
$T_{stg}$	Storage temperature		-65	150	$^\circ\text{C}$
$T_j$	Junction temperature		-	150	$^\circ\text{C}$

**THERMAL RESISTANCES**

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$R_{th j-mb}$	Junction to mounting base		-	1.25	K/W
$R_{th j-a}$	Junction to ambient	in free air	-	60	K/W

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**STATIC CHARACTERISTICS** $T_{mb} = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CES}$	Collector cut-off current <sup>1</sup>	$V_{BE} = 0 \text{ V}; V_{CE} = V_{CESMmax}$	-	-	1.0	mA
$I_{CES}$		$V_{BE} = 0 \text{ V}; V_{CE} = V_{CESMmax}$	-	-	2.0	mA
$I_{EBO}$	Emitter cut-off current	$T_j = 125^\circ\text{C}$	-	-	10.0	mA
$V_{CEO_sust}$	Collector-emitter sustaining voltage	$V_{EB} = 9.0 \text{ V}; I_C = 0 \text{ A}$	400	-	-	V
$V_{CEsat}$	Collector-emitter saturation voltage	$I_B = 0 \text{ A}; I_C = 100 \text{ mA}; L = 25 \text{ mH}$	-	0.8	2.0	V
$V_{BEsat}$	Base-emitter saturation voltage	$I_C = 3.0 \text{ A}; I_B = 0.4 \text{ A}$	-	-	1.3	V
$h_{FE}$	DC current gain	$I_C = 3.0 \text{ A}; I_B = 0.4 \text{ A}$	13	21	30	
$h_{FE}$		$I_C = 1.0 \text{ A}; V_{CE} = 2 \text{ V}$	7.5	11	-	
$h_{FE}$	Gain bands <sup>2</sup> (Acceptance limits)	$I_C = 1.0 \text{ A}; V_{CE} = 2 \text{ V}$	13 18 23	- -	20 25 30	

**DYNAMIC CHARACTERISTICS** $T_{mb} = 25^\circ\text{C}$  unless otherwise specified

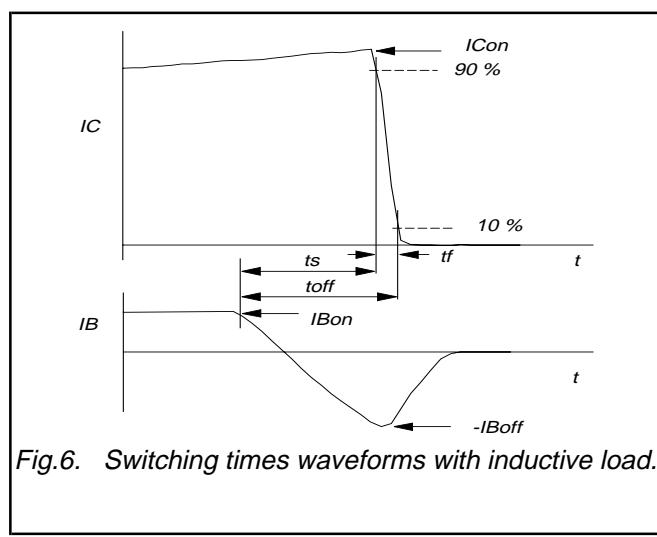
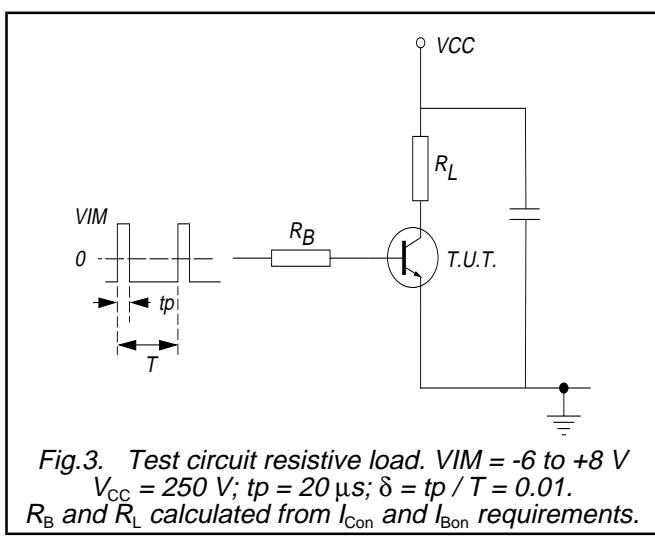
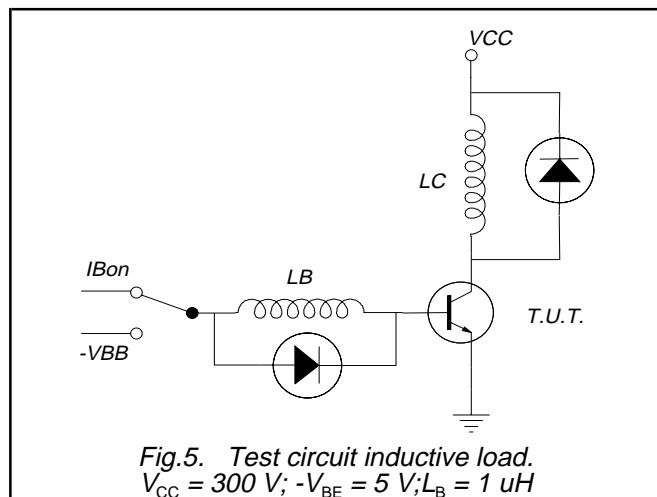
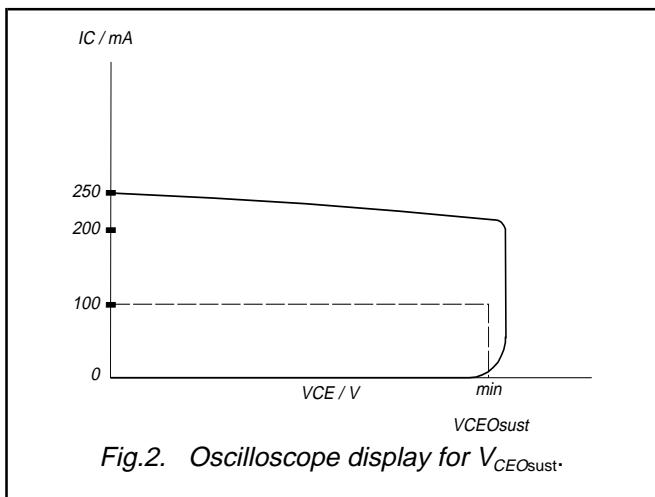
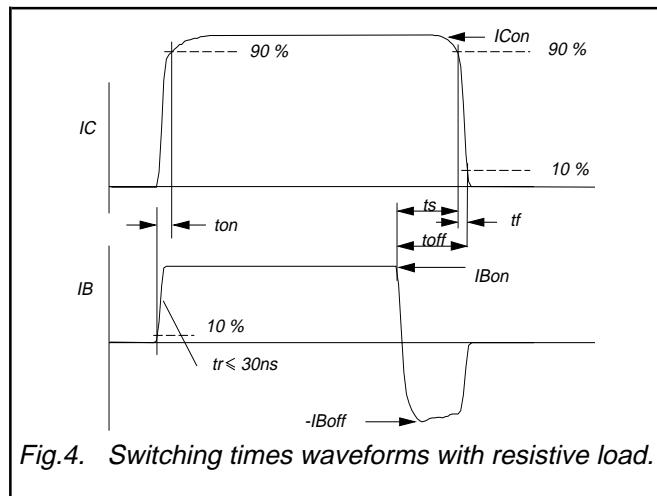
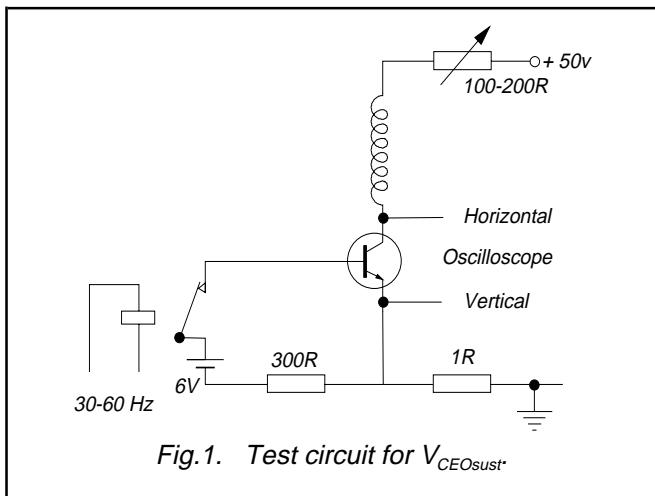
SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$t_s$	Switching times resistive load	$I_{Con} = 3.0 \text{ A}; I_{Bon} = 0.3 \text{ A}; -I_{Boff} = 0.6 \text{ A}$	1.5	2.0	$\mu\text{s}$
$t_f$	Turn-off storage time		0.5	0.8	$\mu\text{s}$
$t_s$	Turn-off fall time				
$t_s$	Switching times inductive load	$I_{Con} = 3.0 \text{ A}; I_{Bon} = 0.3 \text{ A}; L_B = 1 \mu\text{H}; -V_{BB} = 5 \text{ V}$	1.0	1.2	$\mu\text{s}$
$t_f$	Turn-off storage time		60	100	ns
$t_s$	Turn-off fall time	$I_{Con} = 3.0 \text{ A}; I_{Bon} = 0.3 \text{ A}; L_B = 1 \mu\text{H}; -V_{BB} = 5 \text{ V}; T_j = 100^\circ\text{C}$	1.1	1.4	$\mu\text{s}$
$t_f$			120	250	ns

<sup>1</sup> Measured with half sine-wave voltage (curve tracer).<sup>2</sup> Gain Banding.

Product is divided into 3 gain bands for matching purposes.  
The gain band is printed on the device.  
All devices within a device rail will be from the same gain band.  
However, a box may contain rails from more than one band.  
Band quantities are shown on the box label.  
It is not possible to order specific gain bands.

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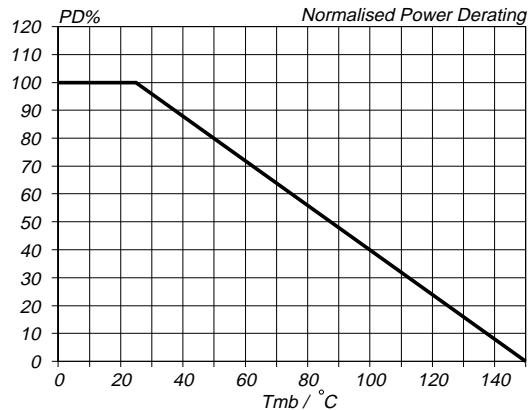


Fig.7. Normalised power dissipation.  
 $PD\% = 100 \cdot PD/PD_{25^\circ C} = f(T_{mb})$

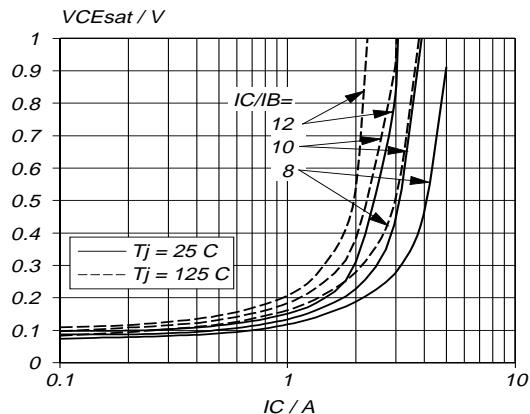


Fig.10. Typical collector-emitter saturation voltage.  
 $V_{CEsat} = f(I_C)$ ; parameter  $I_C/I_B$

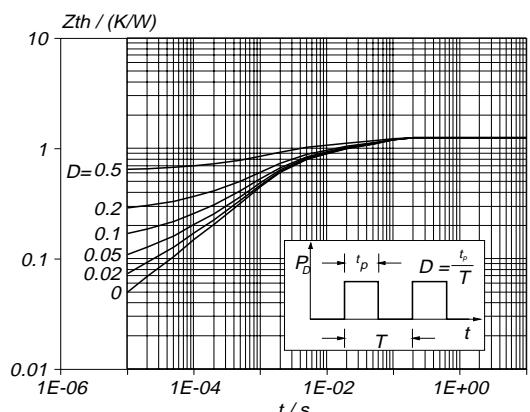


Fig.8. Transient thermal impedance.  
 $Z_{th j-mb} = f(t)$ ; parameter  $D = t_p/T$

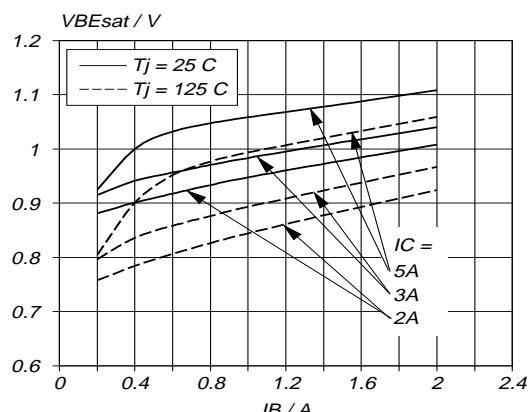


Fig.11. Typical base-emitter saturation voltage.  
 $V_{BEsat} = f(I_B)$ ; parameter  $I_C$

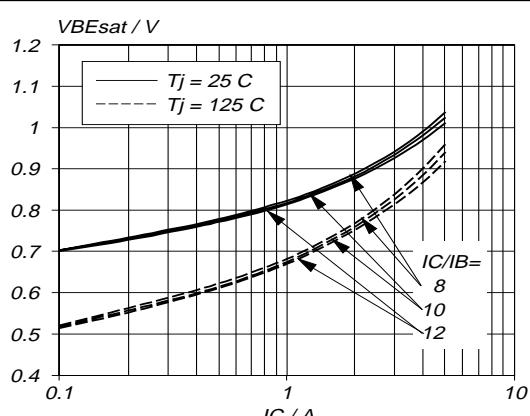


Fig.9. Typical base-emitter saturation voltage.  
 $V_{BEsat} = f(I_C)$ ; parameter  $I_C/I_B$

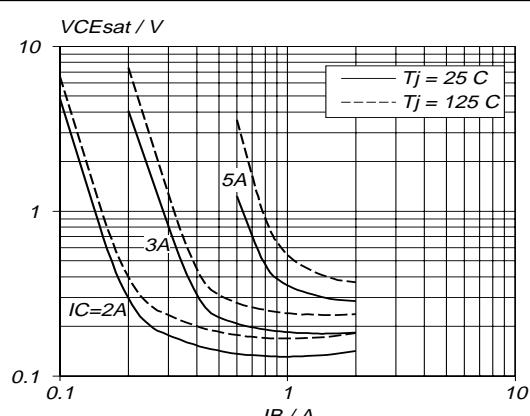


Fig.12. Typical collector-emitter saturation voltage.  
 $V_{CEsat} = f(I_B)$ ; parameter  $I_C$

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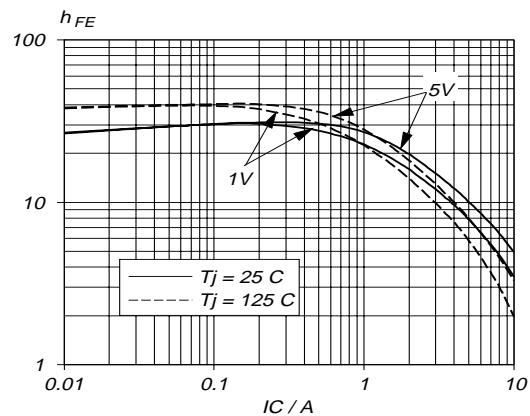


Fig.13. Typical DC current gain.  $h_{FE} = f(I_C)$   
parameter  $V_{CE}$

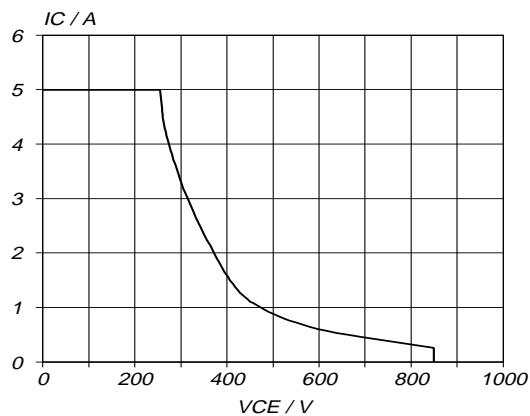


Fig.15. Reverse bias safe operating area.  $T_j \leq T_{j,\max}$

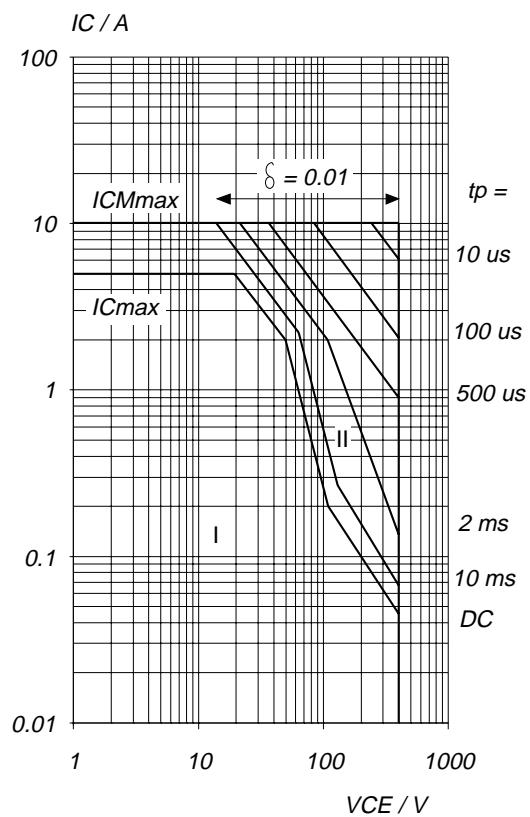


Fig.14. Forward bias safe operating area.  $T_{mb} = 25\text{ }^{\circ}\text{C}$

- I Region of permissible DC operation.
- II Extension for repetitive pulse operation.
- NB: Mounted with heatsink compound and  
 $30 \pm 5$  newton force on the centre of the envelope.

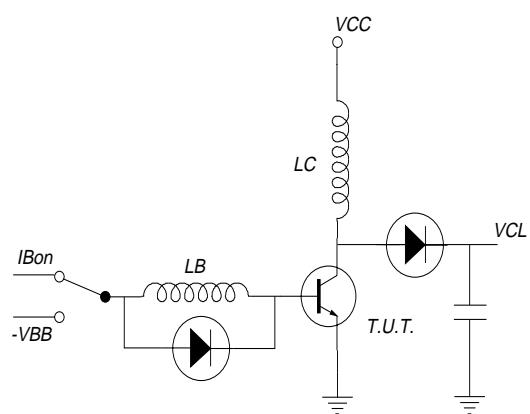


Fig.16. Test circuit RBSOA.  $V_{CC} = 150\text{ V}$ ;  $-V_{BB} = 5\text{ V}$   
 $L_C = 200\text{ }\mu\text{H}$ ;  $V_{CL} \leq 850\text{ V}$ ;  $L_B = 1\text{ }\mu\text{H}$

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**MECHANICAL DATA***Dimensions in mm*

Net Mass: 2 g

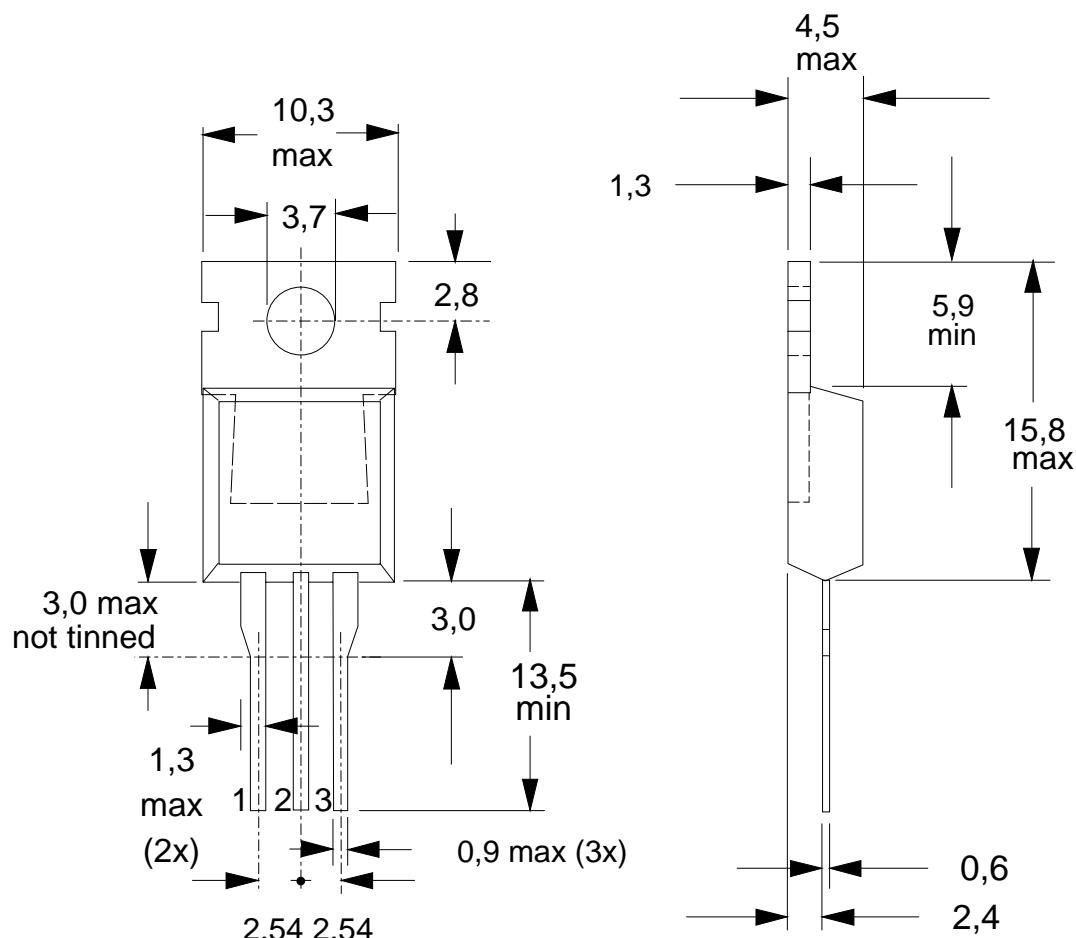


Fig.17. TO220AB; pin 2 connected to mounting base.

**Notes**

1. Refer to mounting instructions for TO220 envelopes.
2. Epoxy meets UL94 V0 at 1/8".

**Silicon Diffused Power Transistor****BUT211****DEFINITIONS**

<b>Data sheet status</b>	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
<b>Limiting values</b>	
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
<b>Application information</b>	
Where application information is given, it is advisory and does not form part of the specification.	
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